

FQP9N50C/FQPF9N50C

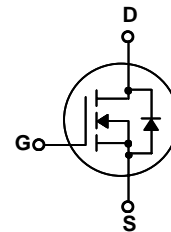
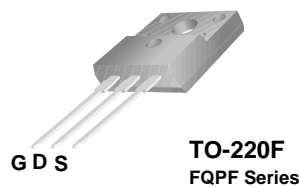
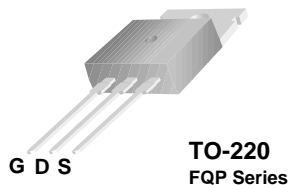
500V N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

Features

- 9 A, 500V, $R_{DS(on)} = 0.8 \Omega @ V_{GS} = 10 V$
- Low gate charge (typical 28 nC)
- Low Crss (typical 24 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | FQP9N50C | FQPF9N50C | Units |
|----------------|---|-------------|-----------|---------------------|
| V_{DSS} | Drain-Source Voltage | 500 | | V |
| I_D | Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$) | 9 | 9 * | A |
| | | 5.4 | 5.4 * | A |
| I_{DM} | Drain Current - Pulsed (Note 1) | 36 | 36 * | A |
| V_{GSS} | Gate-Source Voltage | ± 30 | | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note 2) | 360 | | mJ |
| I_{AR} | Avalanche Current (Note 1) | 9 | | A |
| E_{AR} | Repetitive Avalanche Energy (Note 1) | 13.5 | | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | 4.5 | | V/ns |
| P_D | Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C | 135 | 44 | W |
| | | 1.07 | 0.35 | W/ $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | | $^\circ\text{C}$ |
| T_L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300 | | $^\circ\text{C}$ |

* Drain current limited by maximum junction temperature

Thermal Characteristics

| Symbol | Parameter | FQP9N50C | FQPF9N50C | Units |
|-----------------|---|----------|-----------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | 0.93 | 2.86 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink Typ. | 0.5 | -- | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 62.5 | 62.5 | $^\circ\text{C}/\text{W}$ |

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------------------------------|---|---|-----|------|------|---------------------|
| Off Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 500 | -- | -- | V |
| $\Delta BV_{DSS} / \Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D = 250\ \mu\text{A}$, Referenced to 25°C | -- | 0.57 | -- | V/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$ | -- | -- | 1 | μA |
| | | $V_{DS} = 400\text{ V}, T_C = 125^\circ\text{C}$ | -- | -- | 10 | μA |
| I_{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | 100 | nA |
| I_{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$ | -- | -- | -100 | nA |

On Characteristics

| | | | | | | |
|--------------|-----------------------------------|---|-----|------|-----|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$ | 2.0 | -- | 4.0 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 10\text{ V}, I_D = 4.5\text{ A}$ | -- | 0.65 | 0.8 | Ω |
| g_{FS} | Forward Transconductance | $V_{DS} = 40\text{ V}, I_D = 4.5\text{ A}$ (Note 4) | -- | 6.5 | -- | S |

Dynamic Characteristics

| | | | | | | |
|------------|------------------------------|--|----|-----|------|----|
| C_{iss} | Input Capacitance | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$ | -- | 790 | 1030 | pF |
| C_{oss} | Output Capacitance | | -- | 130 | 170 | pF |
| C_{riss} | Reverse Transfer Capacitance | | -- | 24 | 30 | pF |

Switching Characteristics

| | | | | | | | |
|--------------|---------------------|--|-------------|----|-----|-----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = 250\text{ V}, I_D = 9\text{ A},$ $R_G = 25\ \Omega$ | -- | 18 | 45 | ns | |
| t_r | Turn-On Rise Time | | -- | 65 | 140 | ns | |
| $t_{d(off)}$ | Turn-Off Delay Time | | (Note 4, 5) | -- | 93 | 195 | ns |
| t_f | Turn-Off Fall Time | | (Note 4, 5) | -- | 64 | 125 | ns |
| Q_g | Total Gate Charge | $V_{DS} = 400\text{ V}, I_D = 9\text{ A},$ $V_{GS} = 10\text{ V}$ | -- | 28 | 35 | nC | |
| Q_{gs} | Gate-Source Charge | | (Note 4, 5) | -- | 4 | -- | nC |
| Q_{gd} | Gate-Drain Charge | | (Note 4, 5) | -- | 15 | -- | nC |

Drain-Source Diode Characteristics and Maximum Ratings

| | | | | | | |
|----------|---|---|----|------|-----|---------------|
| I_S | Maximum Continuous Drain-Source Diode Forward Current | -- | -- | 9 | A | |
| I_{SM} | Maximum Pulsed Drain-Source Diode Forward Current | -- | -- | 36 | A | |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0\text{ V}, I_S = 9\text{ A}$ | -- | -- | 1.4 | V |
| t_{rr} | Reverse Recovery Time | $V_{GS} = 0\text{ V}, I_S = 9\text{ A},$ | -- | 335 | -- | ns |
| Q_{rr} | Reverse Recovery Charge | $di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4) | -- | 2.95 | -- | μC |

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 8\text{ mH}, I_{AS} = 9\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 9\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\ \mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

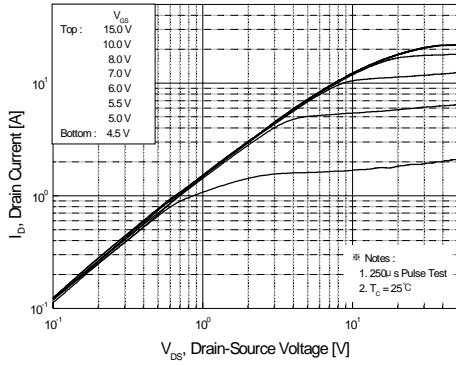


Figure 1. On-Region Characteristics

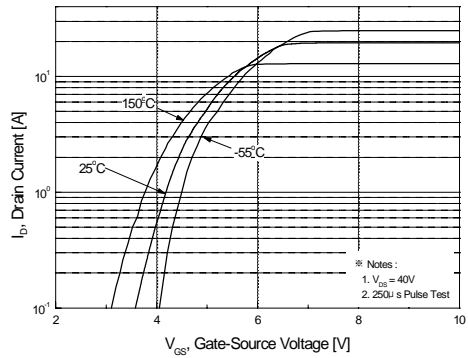


Figure 2. Transfer Characteristics

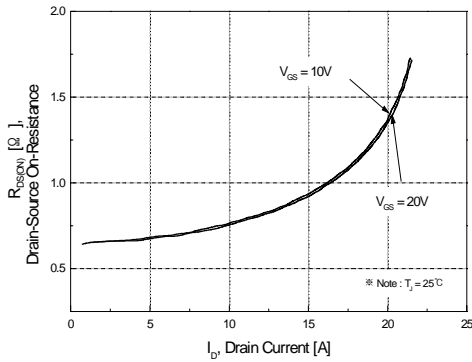


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

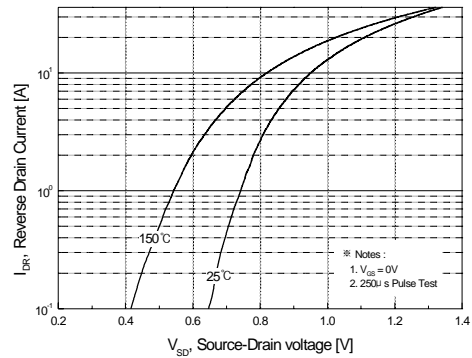


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

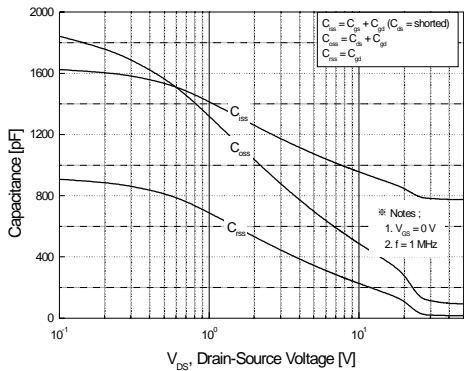


Figure 5. Capacitance Characteristics

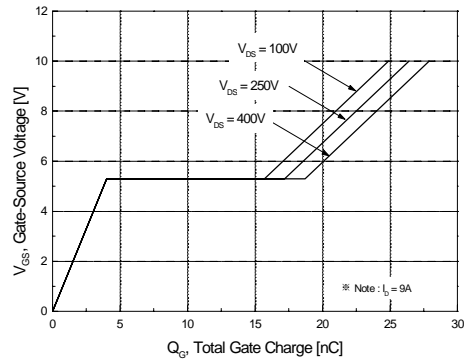


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

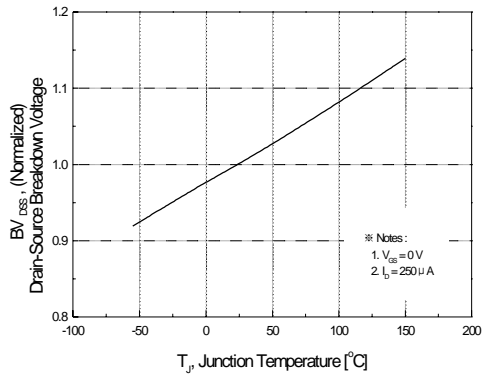


Figure 7. Breakdown Voltage Variation vs Temperature

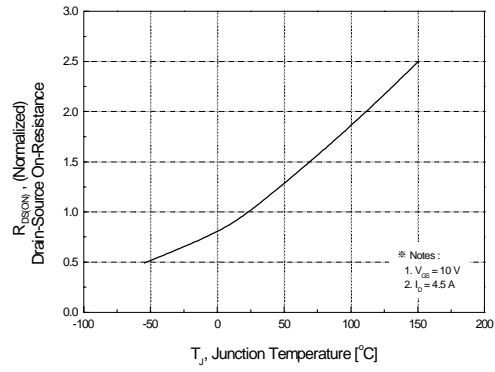


Figure 8. On-Resistance Variation vs Temperature

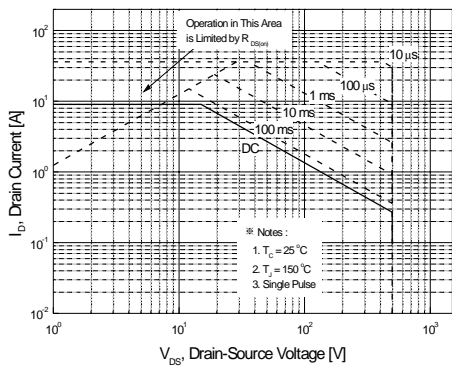


Figure 9-1. Maximum Safe Operating Area for FQP9N50C

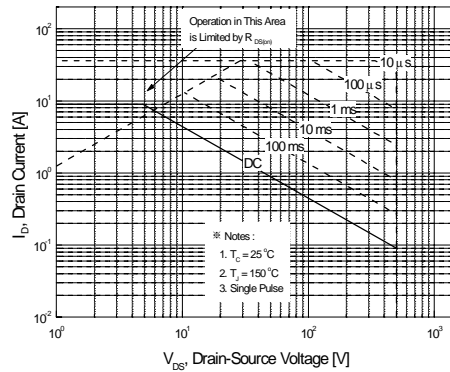


Figure 9-2. Maximum Safe Operating Area for FQPF9N50C

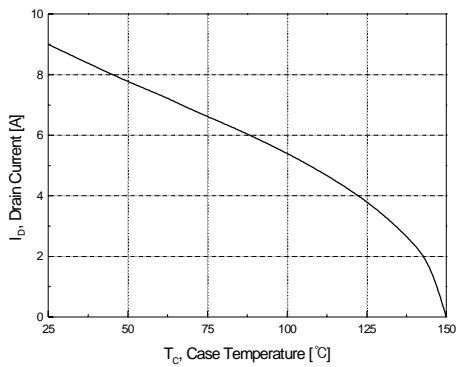


Figure 10. Maximum Drain Current vs Case Temperature

Typical Characteristics (Continued)

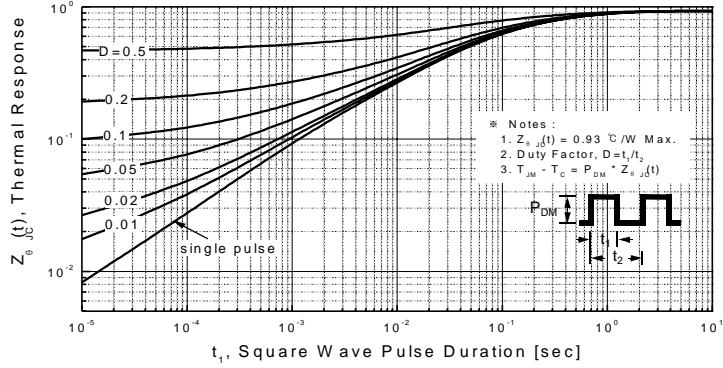


Figure 11-1. Transient Thermal Response Curve for FQP9N50C

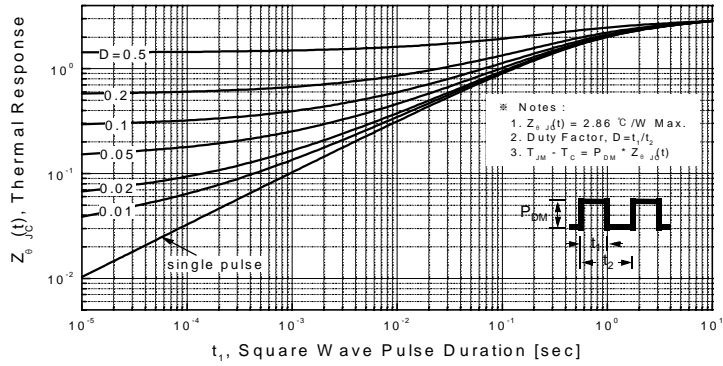


Figure 11-2. Transient Thermal Response Curve for FQPF9N50C

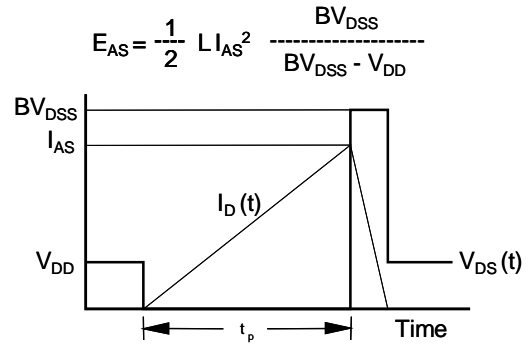
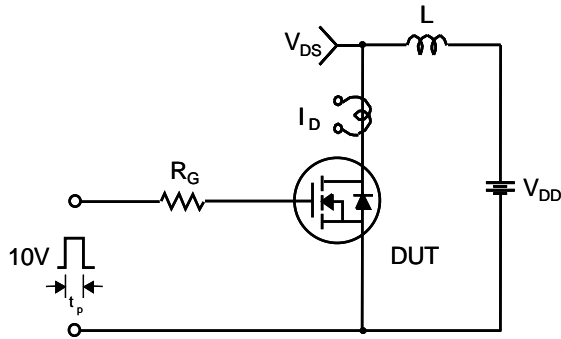
Gate Charge Test Circuit & Waveform



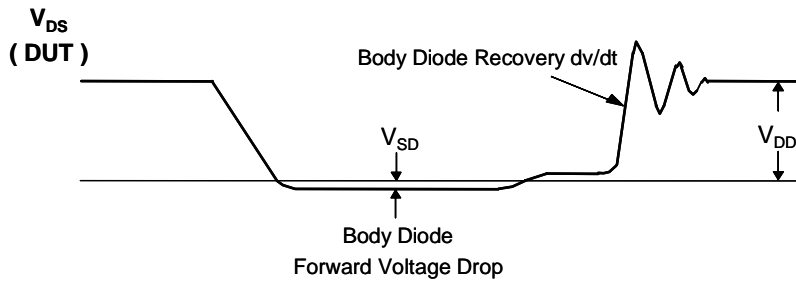
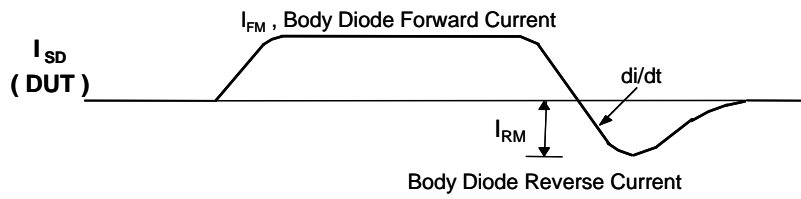
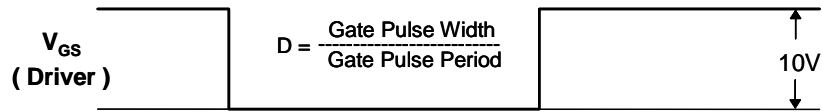
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

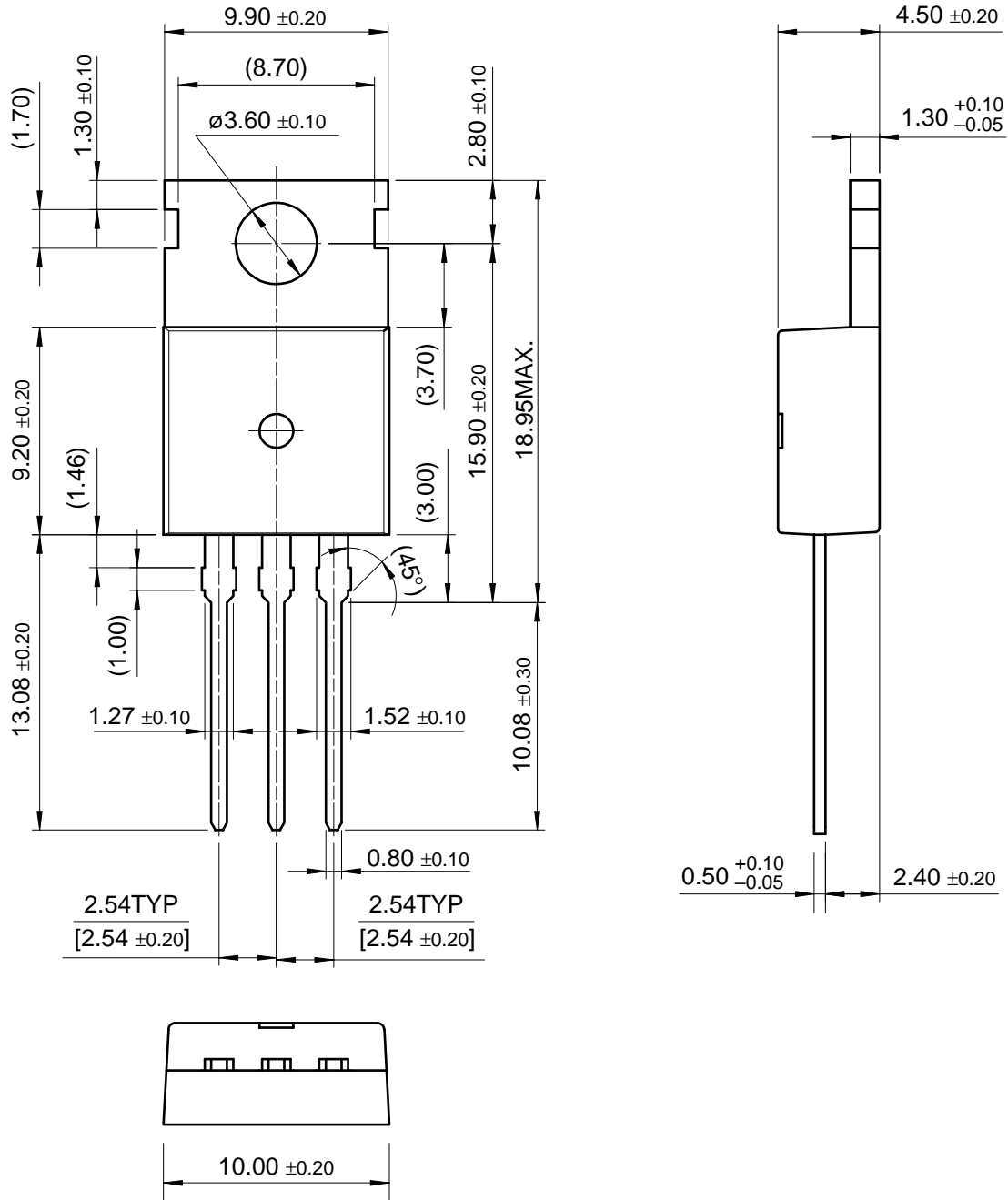


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimensions

TO-220

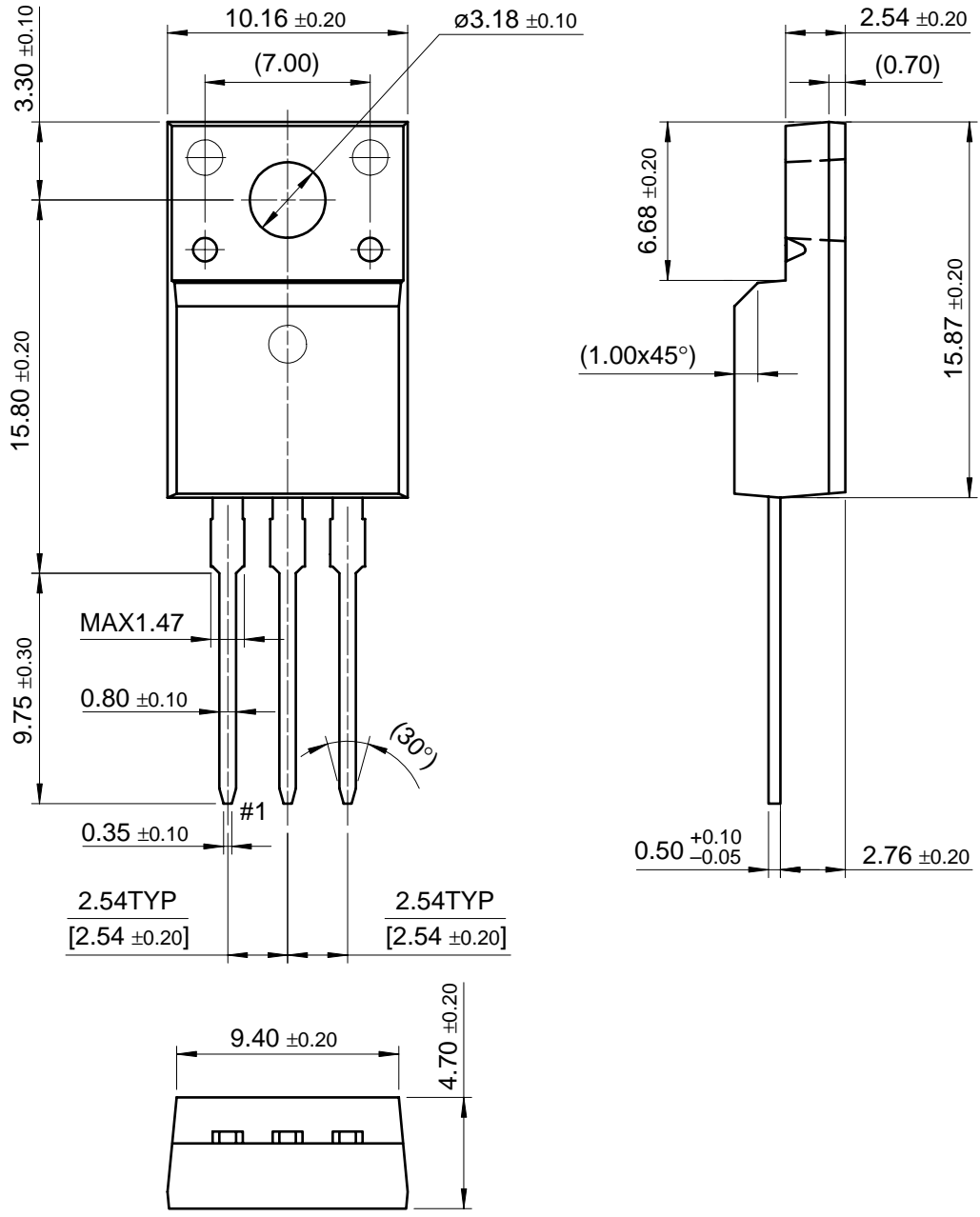


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Dimensions in Millimeters

Package Dimensions (Continued)

TO-220F



FQP9N50C/FQPF9N50C

Dimensions in Millimeters

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FQPF9N50C

500V N-Channel Advance Q-FET C-Series

Contents

- [General description](#)
- [Features](#)
- [Product status/pricing/packaging](#)
- [Order Samples](#)
- [Models](#)
- [Qualification Support](#)

General description

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[back to top](#)

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[back to top](#)

Product status/pricing/packaging

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| Product | Product status | Pb-free Status | Pricing* | Package type | Leads | Packing method | Package Marking Convention** |
|---------------|-----------------|--|----------|-------------------------|-------|----------------|--|
| FQPF9N50C | Full Production |  Full Production | \$1.10 | TO-220F | 3 | RAIL | Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &4 (4-Digit Date Code) Line 2: FQPF Line 3: 9N50C |
| FQPF9N50CT | Full Production |  Full Production | \$1.14 | TO-220F | 3 | RAIL | Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &4 (4-Digit Date Code) |
| FQPF9N50CYDTU | Preliminary |  | \$1.20 | TO-220F | 3 | RAIL | Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &E&3 (3-Digit Date Code) Line 2: FQPF Line 3: 9N50C |

* Fairchild 1,000 piece Budgetary Pricing

** A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a [Fairchild distributor](#) to obtain samples



Indicates product with Pb-free second-level interconnect. For more information [click here](#).

Package marking information for product FQPF9N50C is available. [Click here for more information](#).

[back to top](#)

Models

| Package & leads | Condition | Temperature range | Vcc range | Software version | Revision date |
|-----------------|------------------------------------|-------------------|-----------|------------------|---------------|
| PSPICE | | | | | |
| TO-220F-3 | Electrical/Thermal | -55°C to 150°C | 0V to 50V | OrCAD 10.3 | Jul 27, 2007 |

[back to top](#)

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Click on a product for detailed qualification data

| Product |
|-------------------------------|
| FQPF9N50C |
| FQPF9N50CT |
| FQPF9N50CYDTU |

[back to top](#)

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